

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon (Si)	7440-21-3	0.32087	100.0	23.63
			Subtotal	0.32087	100	23.63
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01978	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06594	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	65.85295	99.87	4,849.6872
			Subtotal	65.93867	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.31986	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.94947	15.0	364.5
	Filler	Silica fused	60676-86-0	24.41741	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.30975	7.0	170.1
			Subtotal	32.99649	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40736	100.0	30
			Subtotal	0.40736	100	30
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00166	100.0	0.12231
	Pure metal	Aluminium (Al)	7429-90-5	0.13357	100.0	9.83664
			Subtotal	0.13523	200	9.95895
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.13089	65.0	9.63934
	Lead alloy	Silver (Ag)	7440-22-4	0.05034	25.0	3.70744
	Lead alloy	Antimony (Sb)	7440-36-0	0.02014	10.0	1.48298
			Subtotal	0.20137	100	14.82976
			Total	99.99999	100	NaN

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